




| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.51mil | 3.3 | |
| 1 | Top Layer | Copper | 1.38mil | | |
| | Dielectric 1 | FR-4 | 5.12mil | 4.2 | |
| 2 | Signal Layer 1 | Copper | 1.38mil | | |
| | Dielectric 2 | FR-4 | 47.24mil | 4.2 | |
| 3 | Signal Layer 2 | Copper | 1.38mil | | |
| | Dielectric 3 | FR-4 | 5.12mil | 4.2 | |
| 4 | Bottom Layer | Copper | 1.38mil | | |
| | Bottom Solder | Solder Resist | 0.51mil | 3.3 | |
| | Bottom Overlay | | | | |



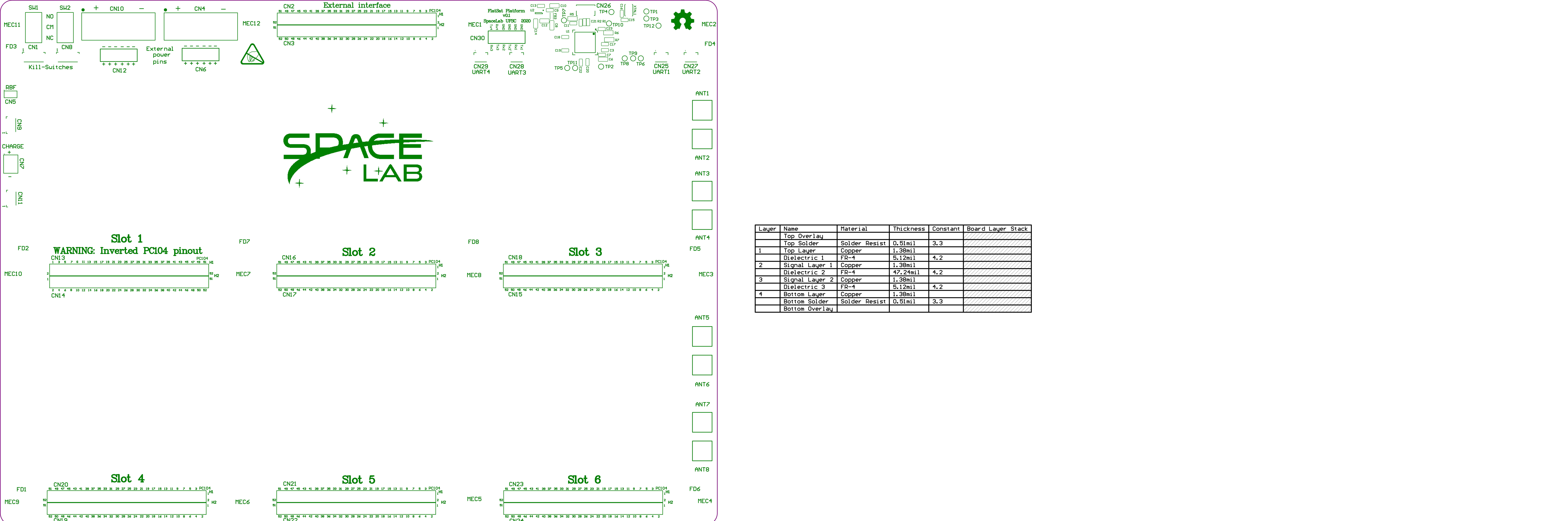
| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.51mil | 3.3 | |
| 1 | Top Layer | Copper | 1.38mil | | |
| | Dielectric 1 | FR-4 | 5.12mil | 4.2 | |
| 2 | Signal Layer 1 | Copper | 1.38mil | | |
| | Dielectric 2 | FR-4 | 47.24mil | 4.2 | |
| 3 | Signal Layer 2 | Copper | 1.38mil | | |
| | Dielectric 3 | FR-4 | 5.12mil | 4.2 | |
| 4 | Bottom Layer | Copper | 1.38mil | | |
| | Bottom Solder | Solder Resist | 0.51mil | 3.3 | |
| | Bottom Overlay | | | | |



| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.51mil | 3.3 | |
| 1 | Top Layer | Copper | 1.38mil | | |
| | Dielectric 1 | FR-4 | 5.12mil | 4.2 | |
| 2 | Signal Layer 1 | Copper | 1.38mil | | |
| | Dielectric 2 | FR-4 | 47.24mil | 4.2 | |
| 3 | Signal Layer 2 | Copper | 1.38mil | | |
| | Dielectric 3 | FR-4 | 5.12mil | 4.2 | |
| 4 | Bottom Layer | Copper | 1.38mil | | |
| | Bottom Solder | Solder Resist | 0.51mil | 3.3 | |
| | Bottom Overlay | | | | |




| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.51mil | 3.3 | |
| 1 | Top Layer | Copper | 1.38mil | | |
| | Dielectric 1 | FR-4 | 5.12mil | 4.2 | |
| 2 | Signal Layer 1 | Copper | 1.38mil | | |
| | Dielectric 2 | FR-4 | 47.24mil | 4.2 | |
| 3 | Signal Layer 2 | Copper | 1.38mil | | |
| | Dielectric 3 | FR-4 | 5.12mil | 4.2 | |
| 4 | Bottom Layer | Copper | 1.38mil | | |
| | Bottom Solder | Solder Resist | 0.51mil | 3.3 | |
| | Bottom Overlay | | | | |




GND

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.51mil | 3.3 | |
| 1 | Top Layer | Copper | 1.38mil | | |
| | Dielectric 1 | FR-4 | 5.12mil | 4.2 | |
| 2 | Signal Layer 1 | Copper | 1.38mil | | |
| | Dielectric 2 | FR-4 | 47.24mil | 4.2 | |
| 3 | Signal Layer 2 | Copper | 1.38mil | | |
| | Dielectric 3 | FR-4 | 5.12mil | 4.2 | |
| 4 | Bottom Layer | Copper | 1.38mil | | |
| | Bottom Solder | Solder Resist | 0.51mil | 3.3 | |
| | Bottom Overlay | | | | |




| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.51mil | 3.3 | |
| 1 | Top Layer | Copper | 1.38mil | | |
| | Dielectric 1 | FR-4 | 5.12mil | 4.2 | |
| 2 | Signal Layer 1 | Copper | 1.38mil | | |
| | Dielectric 2 | FR-4 | 47.24mil | 4.2 | |
| 3 | Signal Layer 2 | Copper | 1.38mil | | |
| | Dielectric 3 | FR-4 | 5.12mil | 4.2 | |
| 4 | Bottom Layer | Copper | 1.38mil | | |
| | Bottom Solder | Solder Resist | 0.51mil | 3.3 | |
| | Bottom Overlay | | | | |

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.51mil | 3.3 | |
| 1 | Top Layer | Copper | 1.38mil | | |
| | Dielectric 1 | FR-4 | 5.12mil | 4.2 | |
| 2 | Signal Layer 1 | Copper | 1.38mil | | |
| | Dielectric 2 | FR-4 | 47.24mil | 4.2 | |
| 3 | Signal Layer 2 | Copper | 1.38mil | | |
| | Dielectric 3 | FR-4 | 5.12mil | 4.2 | |
| 4 | Bottom Layer | Copper | 1.38mil | | |
| | Bottom Solder | Solder Resist | 0.51mil | 3.3 | |
| | Bottom Overlay | | | | |



| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| | Top Solder | Solder Resist | 0.51mil | 3.3 | |
| 1 | Top Layer | Copper | 1.38mil | | |
| | Dielectric 1 | FR-4 | 5.12mil | 4.2 | |
| 2 | Signal Layer 1 | Copper | 1.38mil | | |
| | Dielectric 2 | FR-4 | 47.24mil | 4.2 | |
| 3 | Signal Layer 2 | Copper | 1.38mil | | |
| | Dielectric 3 | FR-4 | 5.12mil | 4.2 | |
| 4 | Bottom Layer | Copper | 1.38mil | | |
| | Bottom Solder | Solder Resist | 0.51mil | 3.3 | |
| | Bottom Overlay | | | | |



| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| 1 | Top Solder | Solder Resist | 0.51mil | 3.3 | |
| 1 | Top Layer | Copper | 1.38mil | | |
| 2 | Dielectric 1 | FR-4 | 5.12mil | 4.2 | |
| 2 | Signal Layer 1 | Copper | 1.38mil | | |
| 2 | Dielectric 2 | FR-4 | 47.24mil | 4.2 | |
| 3 | Signal Layer 2 | Copper | 1.38mil | | |
| 3 | Dielectric 3 | FR-4 | 5.12mil | 4.2 | |
| 4 | Bottom Layer | Copper | 1.38mil | | |
| 4 | Bottom Solder | Solder Resist | 0.51mil | 3.3 | |
| | Bottom Overlay | | | | |



| Symbol | Count | Hole Size | Plated | Hole Type | Drill Layer Pair | Via/Pad | Pad Shape | Template | Description | Hole Tolerance (+) | Hole Tolerance (-) | Hole Length | Routed Path Length |
|------------|-------|---------------------|--------|-----------|--------------------------|---------|-----------|--------------------|-------------|--------------------|--------------------|--------------------|--------------------|
| ○ | 2 | 0.500mm (19.69mil) | PTH | Slot | Top Layer - Bottom Layer | Pad | Rounded | r90_160h50_120r100 | | | | 1.200mm (47.24mil) | 0.700mm (27.56mil) |
| □ | 2 | 0.550mm (21.65mil) | PTH | Slot | Top Layer - Bottom Layer | Pad | Rounded | r125_95h55_85r100 | | | | 0.850mm (33.47mil) | 0.300mm (11.81mil) |
| ◊ | 4 | 4.500mm (177.17mil) | PTH | Round | Top Layer - Bottom Layer | Pad | Rounded | c600h450 | | | | - | - |
| ▼ | 6 | 0.400mm (15.75mil) | PTH | Round | Top Layer - Bottom Layer | Via | Rounded | v80h40m0mx0 | | | | - | - |
| ✖ | 6 | 1.900mm (74.80mil) | PTH | Round | Top Layer - Bottom Layer | Pad | Rounded | c300h190 | | | | - | - |
| ◇ | 8 | 1.700mm (66.93mil) | PTH | Round | Top Layer - Bottom Layer | Pad | Rounded | c240h170 | | | | - | - |
| ☒ | 32 | 1.800mm (70.87mil) | PTH | Round | Top Layer - Bottom Layer | Pad | Rounded | c250h180 | | | | - | - |
| ○ | 38 | 3.200mm (125.98mil) | PTH | Round | Top Layer - Bottom Layer | Pad | Rounded | c600h320 | | | | - | - |
| □ | 40 | 1.000mm (39.37mil) | PTH | Round | Top Layer - Bottom Layer | Pad | (Mixed) | (Mixed) | | | | - | - |
| ▽ | 740 | 0.900mm (35.43mil) | PTH | Round | Top Layer - Bottom Layer | Pad | (Mixed) | (Mixed) | | | | - | - |
| ❖ | 1002 | 0.300mm (11.81mil) | PTH | Round | Top Layer - Bottom Layer | Via | Rounded | (Mixed) | | | | - | - |
| 1880 Total | | | | | | | | | | | | | |

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| 1 | Top Solder | Solder Resist | 0.51mil | 3.3 | |
| 1 | Top Layer | Copper | 1.38mil | | |
| 2 | Dielectric 1 | FR-4 | 5.12mil | 4.2 | |
| 2 | Signal Layer 1 | Copper | 1.38mil | | |
| 2 | Dielectric 2 | FR-4 | 47.24mil | 4.2 | |
| 3 | Signal Layer 2 | Copper | 1.38mil | | |
| 3 | Dielectric 3 | FR-4 | 5.12mil | 4.2 | |
| 4 | Bottom Layer | Copper | 1.38mil | | |
| 4 | Bottom Solder | Solder Resist | 0.51mil | 3.3 | |
| | Bottom Overlay | | | | |



| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| | Top Overlay | | | | |
| 1 | Top Solder | Solder Resist | 0.51mil | 3.3 | |
| 1 | Top Layer | Copper | 1.38mil | | |
| 2 | Dielectric 1 | FR-4 | 5.12mil | 4.2 | |
| 2 | Signal Layer 1 | Copper | 1.38mil | | |
| 2 | Dielectric 2 | FR-4 | 47.24mil | 4.2 | |
| 3 | Signal Layer 2 | Copper | 1.38mil | | |
| 3 | Dielectric 3 | FR-4 | 5.12mil | 4.2 | |
| 4 | Bottom Layer | Copper | 1.38mil | | |
| 4 | Bottom Solder | Solder Resist | 0.51mil | 3.3 | |
| | Bottom Overlay | | | | |